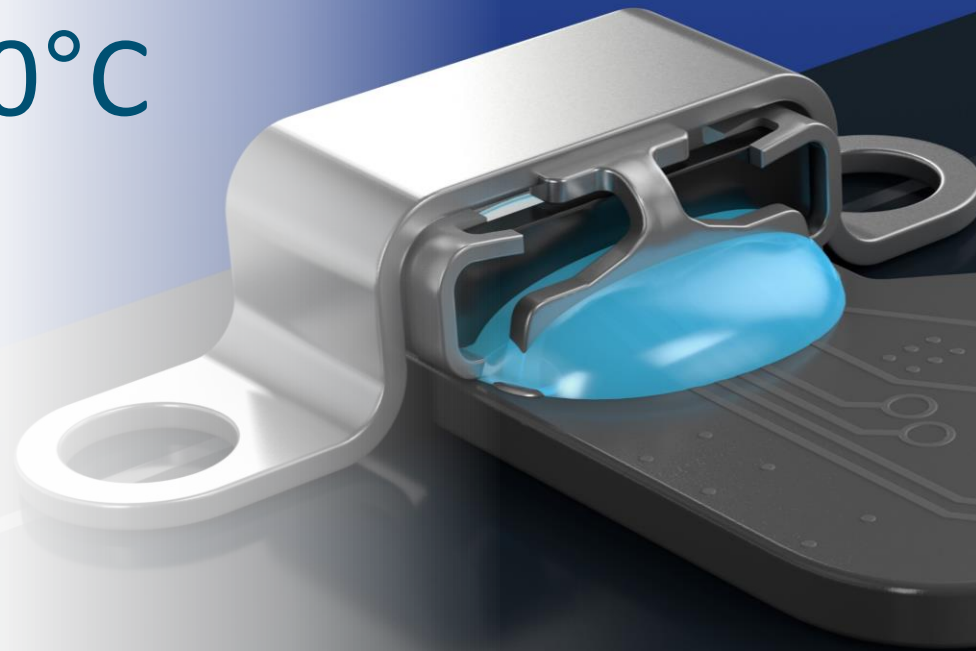


New Panacol epoxies
cure at 60°C



Panacol has developed a range of new one-component epoxy adhesives that cure at very low temperatures. These new adhesives were developed specifically for electronics applications and adhere very well to substrates with low surface energy.

Structalit® 5511, 5521 and 5531 adhesives from Panacol are single component, epoxy resin based, and thermally cure at just 60°C. Curing at higher temperatures will accelerate cure time and add additional strength to the bond. They are particularly suitable for use with temperature sensitive electronic components, including batteries. Each product in this series possesses a unique set of physical properties after reaching full cure. This allows manufacturers the ability to select the best adhesive for their unique component geometries, substrates, and operating functions. All three adhesives possess high purity and low ion content which complies with international standards for electronic and microelectronic component assembly.

The Structalit® 5511 and 5521 adhesives are transparent after cure, possess the lowest viscosity of the three products and both bond well to plastics. The Structalit® 5531 contains a glass filler which enhances its mechanical stability. This stability and its flexibility make the Structalit® 5531 an ideal adhesive for bonds subjected to vibration load and drop testing. This adhesive bonds very well to dissimilar substrates, including steel, aluminum, polycarbonate, and acrylic.

Structalit® adhesives from Panacol generate very high bond strength with materials typically used in the electronics industry. They can also adhere very well to LCP (liquid crystal polymer) and other high-tech plastics with low surface energy. Structalit® adhesives have low halogen content and meet international standards for electronic grade materials.

▶ *[Click here for technical datasheet of Structalit® 5511](#)*